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Pages 1 to 29

**DISCRETE SEMICONDUCTOR COMPONENTS,
HERMETICALLY SEALED**

ESCC Generic Specification No. 5000

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1. INTRODUCTION

1.1 SCOPE

This specification defines the general requirements for the qualification, qualification maintenance, procurement, and delivery of hermetically sealed discrete semiconductor components for space applications. This specification contains the appropriate inspection and test schedules and also specifies the data documentation requirements.

1.2 APPLICABILITY

see attached

This specification is primarily applicable to the granting of qualification approval to a component in accordance with ESCC Basic Specification No. 20100 and the procurement of such components from qualified Manufacturers. It may also be applied for procurement of unqualified components.

2. APPLICABLE DOCUMENTS

The following documents form part of, and shall be read in conjunction with, this specification. The relevant issues shall be those in effect on the date of starting qualification or placing the Purchase Order.

2.1 ESCC SPECIFICATIONS

- No. 20100, Requirements for the Qualification of Standard Electronic Components for Space Application.
- No. 20400, Internal Visual Inspection.
- No. 20500, External Visual Inspection.
- No. 20600, Preservation, Packaging and Dispatch of ESCC ~~Hermetic~~ Components. ← (DCR 391)
- No. 20900, Radiographic Inspection.
- No. 21300, Terms, Definitions, Abbreviations, Symbols and Units.
- No. 21400, Scanning Electron Microscope Inspection of Semiconductor Dice.
- No. 21700, General Requirements for the Marking of ESCC Components.
- No. 22800, ESCC Non-Conformance Control System.
- No. 22900, Total Dose Steady-State Irradiation Test Method.
- No. 23100 → No. 23500, Lead Materials and Finishes for Components for Space Application.
- No. 23800, Electrostatic Discharge Sensitivity Test Method.
- No. 24600, Minimum Quality System Requirements.
- No. 24800, Resistance to Solvents of Marking, Materials and Finishes.

*23100
see attached*

*25100 →
25400
see attached*

For qualification and qualification maintenance or procurement of qualified components, with the exception of ESCC Basic Specifications Nos. 20100, 21700, 22800, and 24600, where Manufacturers' specifications are equivalent to, or more stringent than, the ESCC Basic Specifications listed above, they may be used in place of the latter, subject to the approval of the ESCC Executive. *and 25400*

Such replacements shall be clearly identified in the applicable Process Identification Document (PID).

For procurement of unqualified components, where Manufacturers' specifications are equivalent to or more stringent than the ESCC Basic Specifications listed above, they may be used in place of the latter subject to the approval of the Orderer.

Such replacements may be listed in an appendix to the appropriate Detail Specification at the request of the Manufacturer or Orderer, subject to the approval of the ESCC Executive.

Unless otherwise stated herein, references within the text of this specification to "the Detail Specification" shall mean the relevant ESCC Detail Specification.

Para 1.2

This specification is primarily applicable to the granting of qualification approval to components qualified in

accordance with one of the following ESCC methods:

- Qualification of Standard Components per ESCC Basic Specification No. 20100.
- Technology Flow Qualification per ESCC Basic Specification No. 25400.

It is also primarily applicable to the procurement of components so qualified.

This specification may also be applied to the procurement of unqualified components, recommendations for which are given in ESCC Basic Specification No. 23100.

Para 2.1

- ESCC 23100, ESCC Recommendations for the Evaluation and Procurement of Unqualified Components for

Space Application.

- ESCC 25100, Single Event Effects Test Method and Guidelines.

- ESCC 25400, Requirements for the Technology Flow Qualification of Electronic Components for Space Application.

2.2 OTHER (REFERENCE) DOCUMENTS

- ECSS-Q-70-02, Thermal Vacuum Test for the Screening of Space Materials.
- MIL-STD-750, Test Methods for Semiconductor Devices.
- MIL-STD-883, Test Methods and Procedures for Micro-electronics.

2.3 ORDER OF PRECEDENCE

For the purpose of interpretation and in case of conflict with regard to documentation, the following order of precedence shall apply:

- (a) ESCC Detail Specification.
- (b) ESCC Generic Specification.
- (c) ESCC Basic Specification.
- (d) Other documents, if referenced herein.

3. TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

The terms, definitions, abbreviations, symbols and units specified in ESCC Basic Specification No. 21300 shall apply.

4. REQUIREMENTS

4.1 GENERAL

The test requirements for the component type qualification of a component shall comprise Special In-Process Controls, Wafer Lot Acceptance with radiation tests (if specified), Screening Tests and Component Type Qualification Testing.

The test requirements for procurement of components shall comprise Special In-Process Controls, Wafer Lot Acceptance with radiation tests if required in the Purchase Order, Screening Tests, together with Periodic Testing for qualified components and Lot Validation Testing for qualified (if required in the Purchase Order) and unqualified components (see Chart F1).

*See
attached*

4.1.1 Specifications

For qualification, qualification maintenance, procurement and delivery of components in conformity with this specification, the applicable specifications listed in Section 2 of this document shall apply in total unless otherwise specified herein or in the Detail Specification.

4.1.2 Conditions and Methods of Test

The conditions and methods of test shall be in accordance with this specification, the ESCC Basic Specifications referenced herein and the Detail Specification.

4.1.3 Manufacturer's Responsibility for Performance of Tests and Inspections

The Manufacturer shall be responsible for the performance of tests and inspections required by the applicable specifications. These tests and inspections shall be performed at the plant of the Manufacturer of the components unless it is agreed by the ESCC Executive (for qualification, qualification maintenance, or procurement of qualified components) or the Orderer (for procurement of unqualified components), to use an approved external facility.

4.1 GENERAL

The test requirements for the qualification of a component shall comprise:

- Wafer Lot Acceptance with, if specified, radiation tests
- Special In-Process Controls
- Screening Tests
- Qualification Testing

The requirements for Technology Flow Qualification and the listing of qualified component types shall all be in

accordance with ESCC Basic Specification No. 25400.

The test requirements for procurement of both qualified and unqualified components (See Chart F1) shall

comprise:

- Wafer Lot Acceptance with, if stipulated in the Purchase Order, radiation tests
- Special In-Process Controls
- Screening Tests
- Periodic Testing (for qualified components only)
- Lot Validation Testing if stipulated in the Purchase Order

4.1.4 Inspection Rights

The ESCC Executive (for qualification, qualification maintenance, or procurement of qualified components) or the Orderer (for procurement of unqualified components) reserves the right to monitor any of the tests and inspections scheduled in the applicable specifications. *if stipulated in the Purchase Order*

4.1.5 Pre-encapsulation Inspection Witnessing

see attached [4.1.5.1
4.1.5.2] If required in the Purchase Order, the Orderer may witness or perform the pre-encapsulation inspection and the Manufacturer must notify the Orderer at least 2 working weeks before the commencement of the inspection.

4.2 QUALIFICATION AND QUALIFICATION MAINTENANCE REQUIREMENTS ON A MANUFACTURER

To obtain and maintain the ~~competence~~ qualification of a component, or family of components, a Manufacturer shall satisfy the requirements of ESCC Basic Specification No. 20100.

see attached → To obtain ... etc --

4.3 DELIVERABLE COMPONENTS

see attached [4.3.1
4.3.2] Components delivered to this specification shall be processed and inspected in accordance with the relevant Process Identification Document (PID). Each delivered component shall be traceable to its production lot. Components delivered to this specification shall have satisfactorily completed all the required tests.

ESCC qualified components delivered to this specification shall be produced from lots that are capable of passing all applicable tests, and sequences of tests, that are defined in Chart F4. The Manufacturer shall not knowingly supply components that cannot meet this requirement. In the event that, subsequent to delivery and prior to operational use, a component is found to be in a condition such that it could not have passed these tests at the time of manufacture, this shall be grounds for rejection of the delivered lot.

4.3.1 Lot Failure

3

Lot failure may occur during Special In-Process Controls (Chart F2), Wafer Lot Acceptance (Chart F2), Screening Tests (Chart F3), or Qualification and Periodic Tests (Chart F4).

Should such failure occur during qualification, qualification maintenance or procurement of qualified components the Manufacturer shall initiate the non-conformance procedure in accordance with ESCC Basic Specification No. 22800. The Manufacturer shall notify the Orderer and the ESCC Executive by any appropriate written means, within 5 working days, giving details of the number and mode of failure and the suspected cause. No further testing shall be performed on the failed components. *until so instructed by the ESCC Executive*

Should such failure occur during procurement of unqualified components the Manufacturer shall notify the Orderer by any appropriate written means within 5 working days, giving details of the number and mode of failure and the suspected cause. No further testing shall be performed on the failed components. The Orderer shall inform the Manufacturer within 5 working days of receipt of notification what action shall be taken. *or analysis*

until so instructed by the Orderer.

4.4 MARKING

All components procured and delivered to this specification shall be marked in accordance with ESCC Basic Specification No. 21700.

4.1.5 Customer Source Inspection

4.1.5.1 Pre-Encapsulation Source Inspection

If stipulated in the Purchase Order, the Orderer may perform a source inspection at the Manufacturer's facility prior to encapsulation (e.g. perform Internal Visual Inspection). Details of the inspections to be performed or witnessed and the required period of notification shall be as stipulated in the Purchase Order.

4.1.5.2 Final Source Inspection

If stipulated in the Purchase Order, the Orderer may perform a source inspection at the Manufacturer's facility at the end of Screening or during Lot Validation Testing, if applicable (e.g. witness of final Room Temperature Electrical Measurements). Details of the inspections to be performed or witnessed and the required period of notification shall be as stipulated in the Purchase Order.

Para 4.2

To obtain and maintain the qualification of a component produced using a qualified Technology Flow, a Manufacturer shall satisfy the requirements of ESCC Basic Specification No. 25400.

4.3 DELIVERABLE COMPONENTS

4.3.1 ESCC Qualified Components

Components delivered to this specification shall be processed and inspected in accordance with the relevant Process Identification Document (PID).

4.3.2 ESCC Components

Each component, irrespective of qualification status, identified with an ESCC component number and delivered to this specification shall:

- be traceable to its production lot.
- have satisfactorily completed all the required tests.
- be produced from lots that are considered by the Manufacturer to be capable of passing all applicable tests, and sequences of tests, that are defined in Chart F4. The Manufacturer shall not knowingly supply components that cannot meet this requirement. In the event that, subsequent to delivery and prior to operational use, a component is found to be in a condition such that, demonstrably, it could not have passed these tests at the time of manufacture, this shall be grounds for rejection of the delivered lot.



4.5 MATERIALS AND FINISHES

Specific requirements for materials and finishes are specified in the Detail Specification. Where a definite material or finish is not specified a material or finish shall be used so as to ensure that the component meets the performance requirements of this specification and the Detail Specification. Acceptance or approval of any constituent material or finish does not guarantee acceptance of the finished product.

Unless otherwise specified in the Detail Specification the component shall be hermetically sealed.

All non-metallic materials and finishes, that are not within a hermetically sealed enclosure, of the components specified in the detail specification shall meet the outgassing requirements as outlined in ECSS-Q-70-02.

4.6 RADIATION TESTING

For qualification or qualification maintenance radiation testing shall be performed when specified in the Detail Specification to the total dose level given.

For procurement, as stipulated in the Purchase Order, radiation testing shall be performed to the total dose level given in the Detail Specification or to an alternate level if so stipulated in the Purchase Order.

The qualification status of the procured components shall not be impacted by any change to the total dose level applied.

For procurement any lot of components that fails the specified total dose radiation test level may be accepted to a lower level of radiation subject to satisfactory test results at the lower level. In this case the total dose radiation level letter for the lot shall be modified accordingly.

Total Dose Radiation Testing

4.6.2 see attached.

5. PRODUCTION CONTROL

5.1 GENERAL

The minimum requirements for production control are defined in the Process Identification Document (PID).

Unless otherwise specified in the Detail Specification all lots of components used for qualification and qualification maintenance, Lot Validation Testing and for delivery shall be subject to tests and inspections in accordance with Chart F2x in the sequence shown.

Any components which do not meet these requirements shall be removed from the lot and at no future time be resubmitted to the requirements of this specification.

The applicable test requirements are detailed in the paragraphs referenced in Chart F2.

In the case of lot failure, the manufacturer shall act in accordance with Para. 4.3.1.3

5.2 SPECIAL IN-PROCESS CONTROLS

Internal Visual

5.2.1 Pre-encapsulation Inspection

Pre-encapsulation inspection shall consist of Internal Visual Inspection shall be performed in accordance with Para. 8.1.1

4.6.2 SINGLE EVENT EFFECTS TESTING

For qualification or qualification maintenance SEE testing shall be performed when specified in the Detail Specification. The test requirements shall be as specified in the Detail Specification.

For procurement, as stipulated in the Purchase Order, SEE testing shall be performed as specified in the Detail Specification or in accordance with alternate requirements as stipulated in the Purchase Order.

The qualification status of the procured components shall not be impacted by any SEE test results.



~~Bond Strength and Die Shear tests in accordance with Para. 8.2.~~
 5.3.2 Bond Strength and Die Shear
 Bond Strength and Die Shear tests shall be performed on test samples in accordance with Para. 8.2. A single failure shall be cause for lot failure. These tests are considered as destructive and therefore components so tested shall not form part of the delivery lot.

~~5.2.2~~
 3.3 Dimension Check → Dimension Check shall be performed in accordance with Para. 8.10 on 3 samples only.
 If a failure occurs, the complete lot shall be checked. In the event of any failure a 100% Dimension Check shall be performed.

~~5.2.3~~
 3.4 Weight
 The maximum weight of the component specified in the Detail Specification shall be guaranteed but not tested.

~~5.2.4~~
 3.5 Documentation
 Documentation of Special In-Process Controls shall be in accordance with Para. 9.3.
 6

5.3.2 WAFER LOT ACCEPTANCE

5.3.1
 2 Process Monitoring Review (Qualified Components Only)
 Process monitoring review shall be done in compliance with the Manufacturer's SPC rules described in the PID (for qualification, qualification maintenance or procurement of qualified components).
 A wafer shall be rejected if one or more process control data parameters exceed the allowed distribution as specified in the PID (ditto).

5.3.2
 2 Scanning Electron Microscope (SEM) Inspection
 If specified in the Detail Specification, components supplied to this specification shall be produced from wafer lots that have been subjected to, and successfully met, the Scanning Electron Microscope Inspection requirements in accordance with Para. 8.3.

5.2.3 RADIATION TESTING

5.3.3.1
 2 Total Dose Radiation Testing
 For qualification or qualification maintenance:

- If specified in the Detail Specification, components shall be produced from a wafer lot which has been subjected to and successfully completed Total Dose Radiation Testing in accordance with Para. 8.4 to the total dose level ~~given~~.
 8.4.1 → specified

During procurement:

- If specified in the Detail Specification and ~~required~~ ^{stipulated} in the Purchase Order, components shall be produced from a wafer lot which has been subjected to and successfully completed Total Dose Radiation Testing in accordance with Para. 8.4 to the ~~required~~ ^{stipulated} total dose level.
 8.4.1 stipulated

5.2.3.2 → see attached

5.3.4
 2 Documentation
 Documentation of Wafer Lot Acceptance shall be in accordance with Para. 9.3.
 5

5.2.3.2 Single Event Effects Testing

For qualification or qualification maintenance:

- If specified in the Detail Specification, components shall be produced from a wafer lot which has been subjected to and successfully completed SEE Testing in accordance with Para. 8.4.2.

During procurement:

- If specified in the Detail Specification and stipulated in the Purchase Order, components shall be produced from a wafer lot which has been subjected to and successfully completed SEE Testing in accordance with Para. 8.4.2.

6. SCREENING TESTS

6.1 GENERAL

Unless otherwise specified ~~in the Detail Specification~~, ^{lots of} all components used for qualification and qualification maintenance, Lot Validation Testing, and for delivery, shall be subjected to tests and inspections in accordance with Chart F3. All components shall be serialised prior to the tests and inspections. ^{in the sequence shown.}

~~Unless otherwise specified in the Detail Specification, the tests shall be performed in the order shown.~~

Any components which do not meet these requirements shall be removed from the lot and at no future time be resubmitted to the requirements of this specification.

The applicable test methods and conditions are specified in the paragraphs referenced in Chart F3.

6.2 FAILURE CRITERIA

6.2.1 Environmental and Mechanical Test Failure

The following shall be counted as component failures:- components which fail during tests for which the pass/fail criteria are inherent in the test method, i.e. PIND, Radiographic Inspection, Solderability, Seal. ^{and External Visual Inspection.}

6.2.2 Parameter Drift Failure

The acceptable change limits are shown in Parameter Drift Values in the Detail Specification. A component shall be counted as a parameter drift failure if the changes during High Temperature Reverse Bias Burn-in or during Power Burn-in are larger than the drift values (Δ) specified.

6.2.3 Parameter Limit Failure

A component shall be counted as a limit failure if one or more parameters exceed the limits shown in Room Temperature Electrical Measurements or High and Low Temperatures Electrical Measurements in the Detail Specification.

Any component which exhibits a limit failure prior to the submission to HTRB Burn-in shall be rejected and not counted when determining lot rejection.

6.2.4 Other Failures

A component shall be counted as a failure in any of the following cases:

- ~~External Visual Inspection~~ failure.
- Mechanical failure.
- Handling failure.
- Lost component.

6.3 FAILED COMPONENTS

A component shall be considered as a failed component if it exhibits one or more of the failure modes described in Para. 6.2.

6.4 LOT FAILURE

In the case of lot failure, the Manufacturer shall act in accordance with Para. 4.3.1.

6.4.1 Lot Failure during 100% Testing

If the number of components failed on the basis of the failure criteria specified in Paras. 6.2.2 and 6.2.3 exceeds 5% (rounded upwards to the nearest whole number) of the components submitted to ~~initial~~ *measurements of Parameter Drift Values* of Chart F3, the lot shall be considered as failed.

High Temperature Reverse Bias Burn-in (or Power Burn-in if HTRB Burn-in is not being performed)

If a lot is composed of groups of components of one family defined in one ESCC Detail Specification, but separately identifiable for any reason, then the lot failure criteria shall apply separately to each identifiable group.

6.4.2 Lot Failure during Sample Testing

A lot shall be considered as failed if the number of allowable failures during sample testing as specified ^{herein or} in the Detail Specification, is exceeded.

Unless otherwise specified,

if a lot failure occurs, a 100% testing may be performed but the cumulative percent defective shall not exceed that given in Para. 6.4.1.

No failures are allowed for the Solderability test.

6.5 DOCUMENTATION

Documentation of Screening Tests shall be in accordance with Para. 9.7.

7. QUALIFICATION, QUALIFICATION MAINTENANCE AND LOT VALIDATION TESTING

see attached. →

Requirements of this paragraph are applicable to the tests performed for component type qualification and qualification maintenance and also for Lot Validation Testing.

7.1 ~~COMPONENT TYPE~~ QUALIFICATION TESTING

7.1.1 General

Qualification testing shall be in accordance with the requirements given in Chart F4. The tests of Chart F4 shall be performed on the specified sample, chosen at random from components which have successfully passed the tests in Chart F3. This sample constitutes the Qualification Test Lot.

The Qualification Test Lot is divided into subgroups of tests and all components assigned to a subgroup shall be subjected to all of the tests in that subgroup, in the sequence shown. The applicable test requirements are detailed in the paragraphs referenced in Chart F4.

The conditions governing ~~component type~~ qualification testing are given in ESCC Basic Specification No. 20100. *specified*

7.1.2 Distribution within the Qualification Test Lot

Where a Detail Specification covers a range, or series of components that are considered similar, then the Qualification Test Lot shall be comprised of component types so selected that they adequately represent all of the various mechanical, structural and electrical peculiarities of that range or series.

The distribution shall be as specified by, or agreed with, the ESCC Executive.

7.2 see attached. →

QUALIFICATION WITHIN A TECHNOLOGY FLOW

QUALIFICATION MAINTENANCE (PERIODIC TESTING)

~~Component type~~ qualification is maintained through periodic testing and the test requirements of Para. 7.1 shall apply. For each subgroup the period between successive subgroup testing shall be as given in Chart F4. The conditions governing qualification maintenance are given in ESCC Basic Specification No.

the sample size

specified

Para 7 QUALIFICATION, QUALIFICATION MAINTENANCE AND LOT VALIDATION TESTING
The requirements of this paragraph are applicable to the tests performed on components or test structures as part of qualification or qualification maintenance in accordance with either ESCC Basic Specification No. 20100 or 25400 as applicable. They are also applicable to Lot Validation Testing as part of the procurement of qualified or unqualified components.

7.3 QUALIFICATION WITHIN A TECHNOLOGY FLOW

The qualification of a component produced using a qualified Technology Flow shall be in accordance with ESCC Basic Specification No. 25400.

See attached → 20100.

7.3.4 LOT VALIDATION TESTING

7.3.1 General

For qualified components, Lot Validation Testing as defined in compliance with Chart F4, Subgroup 2, shall only be performed on the procured lot if required in the Purchase Order.

If unqualified components are procured using this specification then the Orderer shall define in the Purchase Order the required subgroups from Chart F4 to be used for Lot Validation Testing.

7.3.2 Distribution within the Sample for Lot Validation Testing

Where the Detail Specification covers a range, or series, of components that are considered similar, then it is only necessary to perform Lot Validation Testing on representative types if a number of different types are procured together. The sample for Lot Validation Testing should be comprised of component types so selected that they adequately represent all of the various mechanical, structural and electrical peculiarities of the components procured from the range or series.

The distribution of component types will vary from procurement to procurement and shall be as required in the Purchase Order.

7.4 FAILURE CRITERIA

The following criteria shall apply to qualification, qualification maintenance and Lot Validation Testing.

7.4.1 Environmental and Mechanical Test Failures

The following shall be counted as component failures:-

Components which fail during tests for which the pass/fail criteria are inherent in the test method, e.g. Seal, Terminal Strength, etc.

7.4.2 Electrical Failures

The following shall be counted as component failures:

Components which fail one or more of the applicable limits at each of the relevant data points specified for environmental, mechanical and endurance testing in Intermediate and End-point Electrical Measurements in the Detail Specification.

7.4.3 Other Failures

A component shall be counted as a failure in any of the following cases:

- Visual inspection failure
- Mechanical failure
- Handling failure
- Lost component

7.5 FAILED COMPONENTS

A component shall be considered as failed if it exhibits one or more of the failure modes detailed in Para. 7.4.

Para 7.2

Qualification of a component, produced using a Technology Flow, is maintained by the maintenance of the Technology Flow Qualification itself in accordance with ESCC Basic Specification No. 25400.

Para. 7.4 LOT VALIDATION TESTING

For procurement of qualified components, Lot Validation Testing is not required and shall only be performed if specifically stipulated in the Purchase Order.

For procurement of unqualified components the need for Lot Validation Testing shall be determined by the Orderer (ref. ESCC Basic Specification No. 23100). Lot Validation Testing shall be performed as stipulated in the Purchase Order.

When Lot Validation Testing is required, it shall consist of the performance of one or more of the tests or subgroup test sequences of Chart F4. The testing to be performed and the sample size shall be as stipulated in the Purchase Order. When procurement of more than one component type

is involved from a family, range or series, the selection of representative samples shall also be stipulated in the Purchase Order.



When requested by the ESCC Executive (for qualification, qualification maintenance or procurement of qualified components) or the Orderer (for procurement of qualified or unqualified components), failure analysis of failed components shall be performed ~~by~~ the Manufacturer and the results provided.

under the responsibility of

Failed components shall be retained at the Manufacturer's plant until the final disposition has been agreed and certified.

7.6
7

LOT FAILURE

For qualification and qualification maintenance, the lot shall be considered as failed if one component in any subgroup of Chart F4 is a failed component based on the criteria given in Para. 7.4.5

For procurement, the lot shall be considered as failed if one component in any test specified for Lot Validation Testing is a failed component based on the criteria given in Para. 7.4.5

In the case of lot failure, the Manufacturer shall act in accordance with Para. 4.3.1.3

7.7
8

QUALIFICATION, QUALIFICATION MAINTENANCE AND LOT VALIDATION TESTING SAMPLES

All tests of Chart F4 are considered to be destructive and therefore components so tested shall not form part of the delivery lot.

7.8
9

DOCUMENTATION

Documentation of qualification, qualification maintenance and Lot Validation Testing shall be in accordance with Para. 9.8.

8. TEST METHODS AND PROCEDURES

If a Manufacturer elects to eliminate or modify a test method or procedure, the Manufacturer is still responsible for delivering components that meet all of the performance, quality and reliability requirements defined in this specification and the Detail Specification.

For a qualified component, documentation supporting the change shall be approved by the ESCC Executive and retained by the Manufacturer. It shall be copied, when requested, to the ESCC Executive. The change shall be specified in an appendix to the Detail Specification and in the PID.

For an unqualified component the change shall be approved by the Orderer. The change may be specified in an appendix to the Detail Specification at the request of the Manufacturer or Orderer, subject to the approval of the ESCC Executive.

8.1 INTERNAL VISUAL INSPECTION

ESCC Basic Specification No. 20400.

8.2 BOND STRENGTH AND DIE SHEAR

8.2.1 Bond Strength

MIL-STD-750, Test Method 2037, Test Condition A or B.

Test Condition B shall only be permitted when Test Condition A cannot be used and never for bond wires of diameter less than 0.127mm.

Test Samples: For Special In-Process Controls 3 test samples shall be selected at random from the lot of components accepted after Internal Visual Inspection.

For Qualification and Periodic Tests 3 test samples shall be selected from the components in subgroup 3 of Chart F4.

If agreed by the ESCC Executive (for qualification or qualification maintenance) or the Orderer (for procurement) the test samples for Special In-Process Controls may have only passed the low magnification phase of the Internal Visual Inspection.

Individual separation forces and categories shall be recorded. A single failure shall be cause for lot failure.

8.2.2 Die Shear

MIL-STD-750, Test Method 2017.

The same test samples submitted to Bond Strength shall be used. Individual separation forces and categories shall be recorded. A single failure shall be cause for lot failure.

8.3 SCANNING ELECTRON MICROSCOPE INSPECTION

Only applicable if specified in the Detail Specification.

ESCC Basic Specification No. 21400.

8.4 RADIATION TESTING

8.4.1 TOTAL DOSE RADIATION TESTING

ESCC Basic Specification No. 22900 to the total dose level specified in the Detail Specification or as required in the Purchase Order.

8.4.2
see attached. →
stipulated

8.5 HIGH TEMPERATURE STABILISATION BAKE

MIL-STD-750, Test Method 1032, Duration: 24 hours at maximum storage temperature rating specified in the Detail Specification.

8.6 TEMPERATURE CYCLING

8.6.1 Screening Tests

MIL-STD-750, Test Method 1051, Test Condition C, 20 cycles at maximum storage temperature rating specified in the Detail Specification.

8.6.2 Qualification and Periodic Tests

Not applicable for axial lead glass diodes.

MIL-STD-750, Test Method 1051, Test Condition C, 100 cycles at maximum storage temperature rating specified in the Detail Specification.

8.7 PARTICLE IMPACT NOISE DETECTION (PIND)

MIL-STD-750, Test Method 2052, Test Condition A. The use of the same attachment medium for the Sensitivity Test Unit (STU) and for the components under test (DUT) is not mandatory.

8.4.2 SINGLE EVENT EFFECTS TESTING

ESCC Basic Specification No. 25100 with test requirements as specified in the Detail Specification or as stipulated in the Purchase Order.

PIND prescreening shall not be performed.

The test frequency shall be selected based on the average internal package height from the graph of Figure 2052-2 of the test method. The average internal package height shall be the distance measured from the floor of the package cavity, excluding the thickness of the die mounted inside the package, to the underside of the package lid. For heights of less than 10mils the test frequency shall be 250Hz and for heights greater than 400mils the test frequency shall be 40Hz.

heights

The lot shall be submitted to the PIND test ^{cycle} procedure a maximum of 5 times.

After each PIND test ^{cycle} procedure, defective devices shall be removed from the lot.

If the cumulative defective devices exceed 25% of the lot, the lot shall be rejected.

After any of the 5 PIND test ^{cycles} procedures, if the number of defective devices does not exceed 1 or is less than 1% of the number of devices submitted to the ^{cycle} procedure the lot shall be accepted.

8.8 SEAL

Glass diodes shall not be painted during Screening until after seal tests are completed. Any paint shall be removed prior to seal tests during Qualification and Periodic Tests.

8.8.1 Seal, Fine Leak

MIL-STD-750, Test Method 1071, Condition H1 or H2.

This test is not applicable to components with a cavity $\leq 0.05\text{ccm}$. For components with cavities $> 0.05\text{ccm}$, the maximum leak rate shall be as follows:

$> 0.05\text{ccm}$ to 0.3ccm	: 5×10^{-8} atm ccm/sec
$> 0.3\text{ccm}$ to 3ccm	: 5×10^{-7} atm ccm/sec
$> 3\text{ccm}$ to 40ccm	: 5×10^{-6} atm ccm/sec

See attached per DR296

8.8.2 Seal, Gross Leak

MIL-STD-750, Test Method 1071, Condition C or K for components with cavities.

MIL-STD-750, Test Method 1071, Condition E for clear glass components without cavities.

8.9 ELECTRICAL MEASUREMENTS

8.9.1 Parameter Drift Values

At each of the relevant data points during Screening Tests, Parameter Drift Values shall be measured as specified in the Detail Specification. All values obtained shall be recorded against serial numbers and the parameter drift calculated.

8.9.2 High and Low Temperatures Electrical Measurements

High and Low Temperatures Electrical Measurements shall be performed as specified in the Detail Specification. All values obtained shall be recorded against serial numbers. Unless otherwise specified measurements shall be performed on a sample of 5 components with 0 failures allowed. Alternatively a 100% inspection may be performed.

In the event of any failure a

(Per Approved DCR286)

8.8.1 Seal, Fine Leak

MIL-STD-750, Test Method 1071, Condition H1 or H2.

This test is not applicable to double plug diodes.

- 8.9.3 Room Temperature Electrical Measurements
Room Temperature Electrical Measurements shall be performed as specified in the Detail Specification. All values obtained shall be recorded against serial numbers.
- 8.9.4 Intermediate and End-Point Electrical Measurements
At each of the relevant data points during Qualification and Periodic Tests Intermediate and End-point Electrical Measurements shall be performed as specified in the Detail Specification. All values obtained shall be recorded against serial numbers and the parameter drift calculated, if specified.
- 8.10 EXTERNAL VISUAL INSPECTION AND DIMENSION CHECK
External Visual Inspection shall be performed in accordance with ESCC Basic Specification No. 20500.

Dimension Check (during Special In-Process Controls only) shall be performed in accordance with ESCC Basic Specification No. 20500 and the Detail Specification on a sample of 3 components. *If a failure occurs the complete lot shall be checked. In the event of any failure a 100% Dimension Check shall be performed.*
- 8.11 MECHANICAL SHOCK
MIL-STD-750, Test Method 2016, 1500g, 0.5ms duration, 5 shocks, planes X1, Y1 and Z1.
- 8.12 VIBRATION
MIL-STD-750, Test Method 2056, 20g, 10-2000Hz, cross over at 50Hz.
- 8.13 CONSTANT ACCELERATION
MIL-STD-750, Test Method 2006, 20000g, planes X1, Y1 and Y2.
- 8.14 THERMAL SHOCK
Only applicable for axial lead glass diodes.

MIL-STD-750, Test Method 1056, Test Condition A, 25 cycles.
- 8.15 MOISTURE RESISTANCE
MIL-STD-750, Test Method 1021.
- 8.16 SOLDERABILITY
For procurement lots: 5 samples. A single failure shall be cause for lot failure.

MIL-STD-750, Test Method 2026, to be performed on all terminals.

Solderability testing may be performed on empty packages or electrical rejects. The test samples used must be of the same package type and must have been manufactured using the same process, at the same time and have been subjected to the same screening as the packages of the delivery lot with which they are associated.

For components with gold plated lead finish activated fluxes (RMA, RA and OA) may be used but shall be immediately cleaned off after dipping using an acceptable solvent.

Solderability testing is classed as destructive and therefore components so tested shall not form part of



the delivery lot.

8.17 PERMANENCE OF MARKING
ESCC Basic Specification No. 24800.

8.18 TERMINAL STRENGTH
MIL-STD-883, Test Method 2004, Test Condition D for chip carrier packages.

MIL-STD-750, Test Method 2036 for all other packages. Test Condition as specified in the Detail Specification.

8.19 OPERATING LIFE
Bipolar Devices: MIL-STD-750, Test Method 1026.

MOSFETs: MIL-STD-750, Test Method 1042, Conditions A and B

All other Devices: The test method shall be as specified in the Detail Specification.

- Duration: 2000 hours.
- Conditions: As specified in Operating Life in the Detail Specification.
- Data Points
As specified in Intermediate and End-^Ppoint Electrical Measurements in the Detail Specification at 0 hours, 1000 ± 48 hours and 2000 ± 48 hours. If drift values are specified, the drift shall always be related to the 0-hour measurement.

8.20 HIGH TEMPERATURE REVERSE BIAS BURN-IN
Diodes and Rectifiers: MIL-STD-750, Test Method 1038, Test Condition A.

Bipolar Transistors: MIL-STD-750, Test Method 1039, Test Condition A.

MOSFETs: The test method shall be as specified in the Detail Specification.

All other Devices: The test method shall be as specified in the Detail Specification.

- Duration and Test Conditions
As specified in High Temperature Reverse Bias Burn-in in the Detail Specification. Unless otherwise specified the duration shall be:

MOSFETs: 48 hours minimum
All other devices: 12 hours minimum

- Data Points
As specified in the Parameter Drift Values in the Detail Specification at 0 hours and T (+24 -0) hours (where T is the specified duration). ^(initial) Drift shall be related to the initial measurement.



8.21 POWER BURN-IN

Diodes and Rectifiers: MIL-STD-750, Test Method 1038, Test Condition B.

Bipolar Transistors: MIL-STD-750, Test Method 1039, Test Condition B.

Thyristors: MIL-STD-750, Test Method 1040, Test Condition B.

MOSFETs: The test method shall be as specified in the Detail Specification.

All other Devices: The test method shall be as specified in the Detail Specification.

- Duration
Unless otherwise specified in the Detail Specification, components shall be subjected to a total Power Burn-in period of 168 hours minimum and 264 hours maximum.
- Test Conditions
As specified in Power Burn-in in the Detail Specification.
- Data Points
As specified in Parameter Drift Values in the Detail Specification at T (+24 -0) hours (where T is the specified duration).

If High Temperature Reverse Bias Burn-in is not being performed, the 0 hours (initial) measurement is also required. *Drift shall be related to the initial measurement for Power Burn-in.*

8.22 VERIFICATION OF SAFE OPERATING AREA

If specified in the Detail Specification, a verification of the safe operating area shall be performed. The specified Test Method(s), specific conditions and limits shall be as given in the Detail Specification.

The Test Method(s) shall be selected from the following:

Bipolar Transistors :	Maximum Continuous ^{dc} ac	: MIL-STD-750, Test Method 3051.
	Pulsed	: MIL-STD-750, Test Method 3052.
	Switching	: MIL-STD-750, Test Method 3053. The load conditions shall also be specified.

MOSFETs and Insulated Gate Bipolar Transistors (IGBT): MIL-STD-750, Test Method 3474.

All other Devices: The test method shall be as specified in the Detail Specification.

8.23 RADIOGRAPHIC INSPECTION

Not applicable for diodes with transparent packages.

ESCC Basic Specification No. 20900.

9. DATA DOCUMENTATION

9.1 GENERAL

For the qualification, qualification maintenance and procurement for each lot a data documentation package shall exist in a printed or electronic form.

This package shall be compiled from:

- (a) Cover sheet (or sheets).
- (b) List of equipment (testing and measuring).
- (c) List of test references.
- (e) (d) Special In-Process Controls data (Chart F2).
- (d) (e) Wafer Lot Acceptance data (Chart F2) (when applicable).
- (f) Screening Tests data (Chart F3).
- (g) Qualification and Periodic Tests data including Lot Validation Testing data (when applicable) (Chart F4).
- (h) Failed components list and failure analysis report (when applicable).
- (i) Certificate of Conformity.

Items (a) to (i) inclusive shall be grouped, preferably as subpackages and, for identification purposes, each page shall include the following information:

- ESCC Component Number.
- Manufacturer's name.
- Lot identification.
- Date of establishment of the document.
- Page number.

Whenever possible, documentation should preferably be ^{available} ~~supplied~~ in electronic format suitable for reading using a compatible PC. The format supplied shall be legible, durable and indexed. The preferred storage ~~media are 3 1/2 inch diskettes or CD-ROMs~~ ^{medium is} and the preferred file format ~~are ASCII or PDF.~~ ^{is}

9.1.1 Qualification and Qualification Maintenance

In the case of qualification or qualification maintenance, the items listed in Para. 9.1(a) to (i) are required.

9.1.2 Component Procurement and Delivery

For all deliveries of components procured to this specification, the following documentation shall be supplied:

- (a) Cover sheet (if all of the information is not included on the Certificate of Conformity).
- (b) Certificate of Conformity (including range of delivered serial numbers).

9.1.3 Additional Documentation

The Manufacturer shall deliver additional documentation containing data and reports to the Orderer, if ~~required~~ ^{stipulated} in the Purchase Order.

9.1.4 Data Retention/Data Access

If not delivered, all data shall be retained by the Manufacturer for a minimum of 5 years during which time it shall be available for review, if requested, by the Orderer or the ESCC Executive (for qualified components).

9.2 COVER SHEET(S)

The cover sheet(s) of the data documentation package shall include as a minimum:

- (a) Reference to the Detail Specification, including issue and date.
- (b) Reference to the applicable ESCC Generic Specification, including issue and date.
- (c) ESCC Component Number and the Manufacturers part type number.
- (d) Lot identification.
- (e) Range of delivered serial numbers.
- (f) Number of the Purchase Order.
- (g) Radiation testing level (if applicable).
- (h) Information relative to any additions to this specification and/or the Detail Specification.
- (i) Manufacturer's name and address.
- (j) Location of the manufacturing plant (specify place of diffusion, assembly and test).
- (k) Signature on behalf of Manufacturer.
- (l) Total number of pages of the data package.

9.3 LIST OF EQUIPMENT USED

A list of equipment used for tests and measurements shall be prepared, ~~if not in accordance with the data given in the PID.~~ Where applicable, this list shall contain inventory number, Manufacturer's type number, serial number, etc. This list shall indicate for which tests such equipment was used.

9.4 LIST OF TEST REFERENCES

This list shall include all Manufacturer's references or codes which are necessary to correlate the test data provided with the applicable tests specified in the tables of the Detail Specification.

9.5 SPECIAL IN-PROCESS CONTROLS DATA (CHART F2)

A test result summary shall be compiled, showing the total number of components submitted to, and the total number rejected after each of the tests. For the Bond Strength and Die Shear tests, the separation forces and categories shall be recorded.

9.6 WAFER LOT ACCEPTANCE DATA (CHART F2)

Data of SEM Inspection shall be prepared in accordance with the requirements of ESCC Basic Specification No. 21400 (if specified).

Radiation test report^s shall be prepared in accordance with the requirements of ESCC Basic Specification No. 22900₁ (if specified).

and/or 25100

9.7 SCREENING TESTS DATA (CHART F3)

A test result summary shall be compiled showing the total number of components submitted to and the total number rejected after each of the tests. For each test requiring electrical measurements the results shall be recorded against component serial number. Component drift calculations shall be recorded for each specified test against component serial number. For Radiographic Inspection photographic results shall be recorded against component serial number (as applicable).

9.8 QUALIFICATION AND PERIODIC TESTS DATA (CHART F4)

9.8.1 Qualification Testing

A test result summary shall be compiled showing the components submitted to and the number rejected after each test in each subgroup. Component serial numbers for each subgroup shall be identified. For each test requiring electrical measurements the results shall be recorded against component serial number. Where a drift value is specified during a test the drift calculation shall be recorded against component serial number.

9.8.2 Periodic Testing for Qualification Maintenance

A test result summary shall be compiled showing the components submitted to and the number rejected after each test in each subgroup. Component serial numbers for each subgroup shall be identified. For each test requiring electrical measurements the results shall be recorded against component serial number. Where a drift value is specified during a test the drift calculation shall be recorded against component serial number.

In addition to the full test data a report shall be compiled for each subgroup of Chart F4 to act as the most recent Periodic Testing summary. These reports shall include a list of all tests performed in each subgroup, the ESCC Component Numbers and quantities of components tested, a statement confirming all the results were satisfactory, the date the tests were performed and a reference to the full test data.

9.8.3 Lot Validation Testing

A test result summary shall be compiled showing the components submitted to and the number rejected after each test in each subgroup (as applicable). Component serial numbers for each subgroup shall be identified. For each test requiring electrical measurements the results shall be recorded against component serial number. Where a drift value is specified during a test the drift calculation shall be recorded against component serial number.

9.9 FAILED COMPONENTS LIST AND FAILURE ANALYSIS REPORT

The failed components list and failure analysis report shall provide full details of:

(a) The reference and description of the test or measurement performed as defined in this specification and/or the Detail Specification during Special In-Process Controls, Wafer Lot Acceptance, Screening Tests and Qualification and Periodic Tests.

(b) ~~The serial number (if applicable) of the failed component.~~

(c) The failed parameter and the failure mode of the component.

(d) Detailed failure analysis (if requested by the ESCC Executive or Orderer).

(b) Traceability information including serial number (if applicable) of the failed component.

9.10 CERTIFICATE OF CONFORMITY

A Certificate of Conformity shall be established ~~as defined in~~ ESCC Basic Specification No. 20100.

in accordance with the requirements of

10. DELIVERY

For procurement, for each order, the items forming the delivery are:

(a) The delivery lot.

(b) The components used for Lot Validation Testing ^{as} ~~(when applicable)~~, but not forming part of the delivery lot, *if stipulated in the Purchase Order.*

(c) The relevant documentation in accordance with the requirements of ~~Section 9~~ *Section 9, Paras. 9.1.2 and 9.1.3.*



In the case of a component for which a valid qualification is in force, all data of all components submitted to Lot Validation Testing shall also be copied, when requested, to the ESCC Executive.

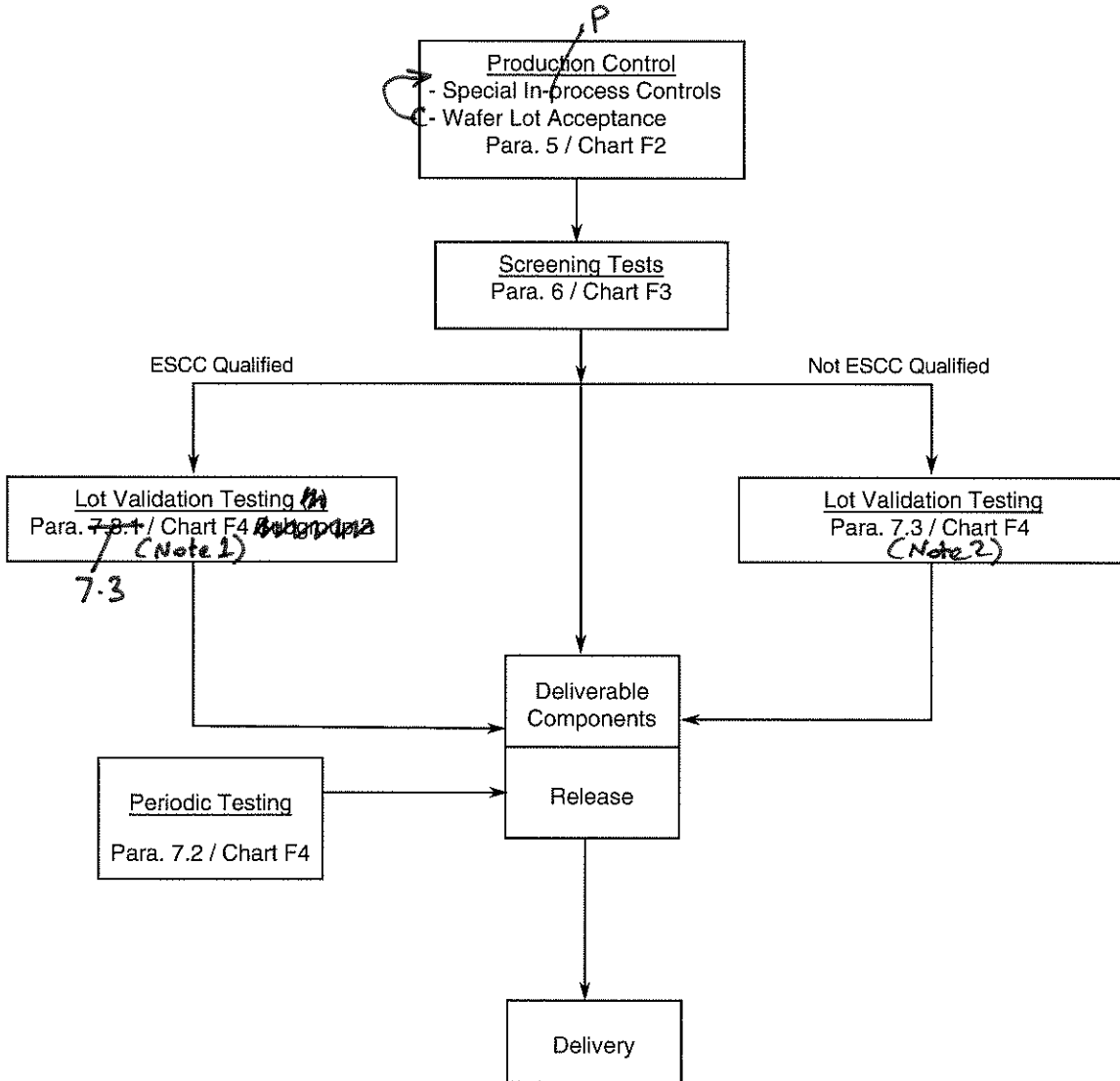
For qualification or qualification maintenance, the disposition of the ~~test lot~~ ^{Qualification Test lot} and its related documentation shall be as specified in ESCC Basic Specification No. 20100 and the relevant paragraphs of Section 9 of this specification.

11. PACKAGING AND DISPATCH

The packaging and dispatch of components to this specification shall be in accordance with the requirements of ESCC Basic Specification No. 20600.

12. **CHARTS**

12.1 **CHART F1 - GENERAL FLOW FOR PROCUREMENT**



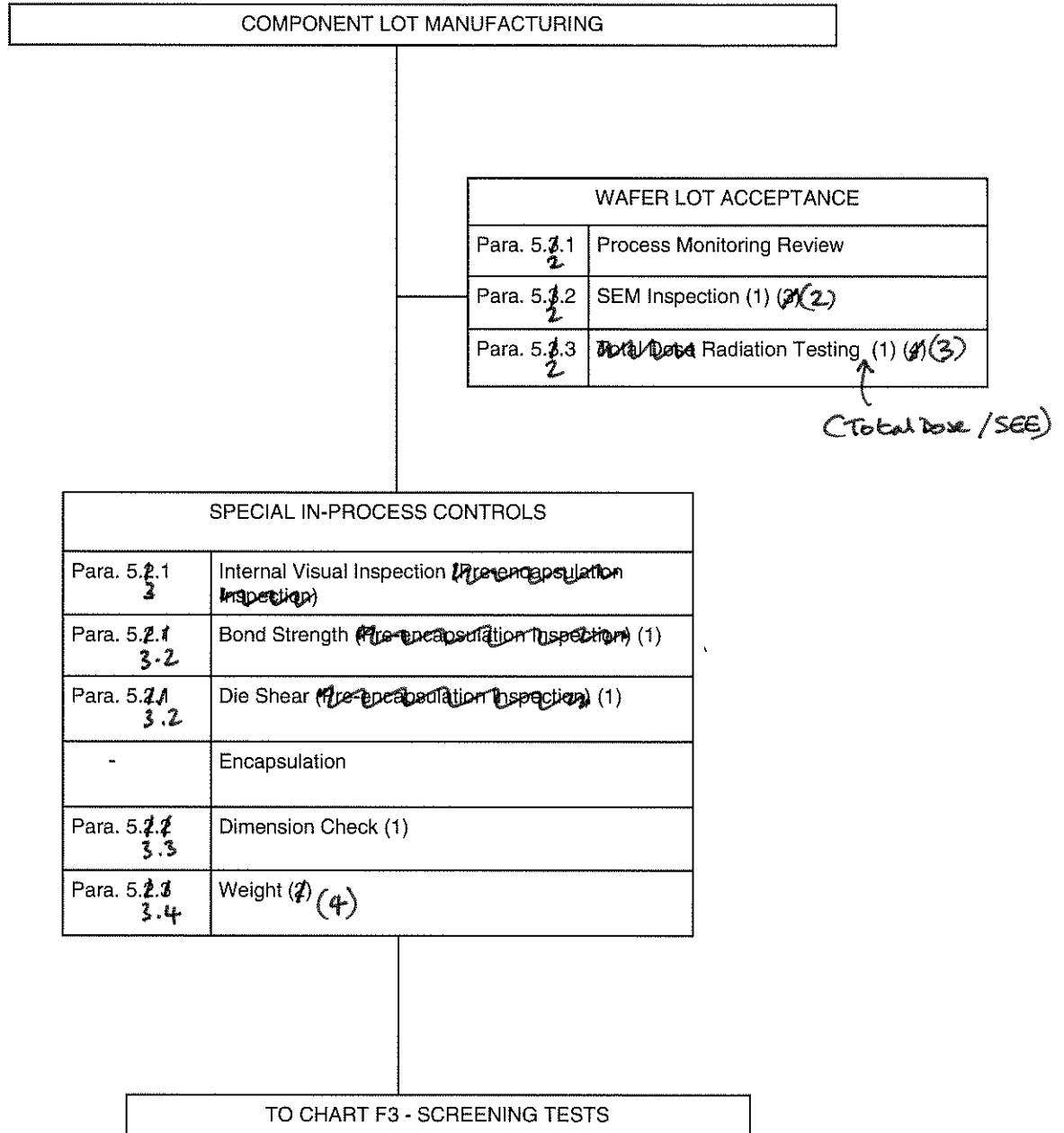
NOTES:

1. Lot Validation Testing is ~~optional~~ *not required* for qualified components and ~~shall only be performed if required in the Purchase Order.~~ *unless specifically stipulated in*
2. *See attached.*

Chart F1 notes:

2. For unqualified components the need for Lot Validation Testing shall be determined by the Orderer and the required testing shall be as stipulated in the Purchase Order (Ref. ESCC Basic Specification No. 23100).

12.2 CHART F2 - PRODUCTION CONTROL



NOTES:

1. Performed on a sample basis.
 - 4 2. Guaranteed but not tested.
 - 2 3. If specified in the Detail Specification.
 - 3 4. If specified in the Detail Specification and ~~required~~ required in the Purchase Order.
- stipulated

12.3

CHART F3 - SCREENING TESTS

<i>COMPONENTS FROM PRODUCTION CONTROL</i>		
Para. 8.22	Verification of Safe Operating Area	(2)
Para. 8.5	High Temperature Stabilisation Bake	
Para. 8.6.1	Temperature Cycling	
Para. 8.7	Particle Impact Noise Detection (PIND)	
Para. 8.9.1	Parameter Drift Values (Initial Measurements)	
Para. 8.20	High Temperature Reverse Bias Burn-in	
Para. 8.9.1	Parameter Drift Values (Final Measurements for HTRB; Initial Measurements for Power Burn-in)	(3)
Para. 8.21	Power Burn-in	
Para. 8.9.1	Parameter Drift Values (Final Measurements)	(3)
Para. 8.9.2	High and Low Temperatures Electrical Measurements	(3) (4)
-	Hot Solder Dip (if applicable)	(5)
Para. 8.9.3	Room Temperature Electrical Measurements	(3) (6)
Para. 6.4.1	Check for Lot Failure	(7)
Para. 8.23	Radiographic Inspection	(8)
<i>Para. 8.8.1 and Para. 8.8.2</i>	Seal (Fine and Gross Leak)	
Para. 8.10	External Visual Inspection	
Para. 8.16	Solderability	(3) (4)

Para 6.1 Serialised. (1)

Burn-in

Para. 8.8 →

TO CHART F4 WHEN APPLICABLE

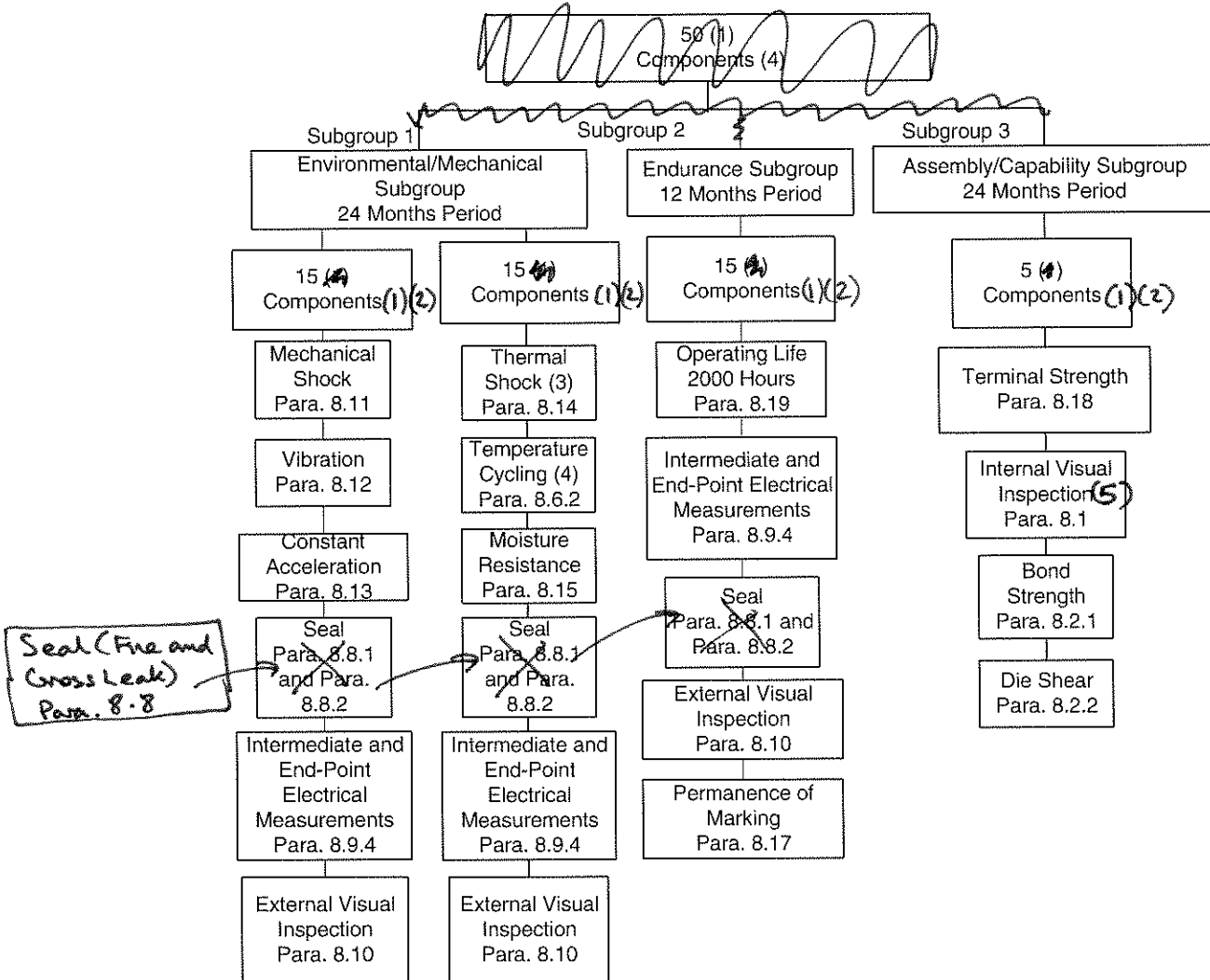
NOTES:

1. All components shall be serialised prior to Screening Tests.
2. If specified in the Detail Specification. Verification of Safe Operating Area may be performed at any

- point prior to Initial measurements of Parameter Drift Values.
3. The lot failure criteria of Para. 6.4 apply to this test.
 4. Performed on a sample basis.
 5. For components with hot solder dip final lead finish the hot solder dip processing shall be performed at any time prior to Room Temperature Electrical Measurements during Screening Tests. The requirements for hot solder dip are specified in ESCC Basic Specification No. 23500.
 6. Measurements of Parameter Drift Values need not be repeated in Room Temperature Electrical Measurements.
 7. Check for Lot Failure shall take into account all electrical parameter failures that may occur during Screening Tests in accordance with Para. 8.9.1, 8.9.2, 8.9.3 subsequent to HTRB Burn-in.
 8. Radiographic Inspection may be performed at any point during Screening Tests. It is not applicable for diodes with transparent packages.

after serialisation

12.4 CHART F4 - QUALIFICATION AND PERIODIC TESTS



NOTES:

1. For distribution within the subgroups see Para. 7.1.2 for Qualification and qualification maintenance and 7.3 for hot Validation Testing.
2. No failures are permitted.
3. Only applicable to axial lead glass diodes.
4. Not applicable to axial lead glass diodes.
5. The components shall be decapsulated using suitable means to facilitate Internal Visual Inspection, Bond Strength and Die Shear.